	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△						△					
△						△					

APPLICABLE STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-35 °C TO +85 °C(NOTE1)	STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE3)
	OPERATING MOISTURE RANGE	20 %TO 80 %(NOTE2)	STORAGE MOISTURE RANGE	40 %TO 70 %(NOTE3)
	CURRENT	1 A	VOLTAGE	150 V AC(DC)

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	×	×
MARKING	CONFIRMED VISUALLY.		×	×
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	30 mΩ MAX.	×	—
CONTACT RESISTANCE MILLIVOLT LEVEL METHOD.	20 mV MAX, 1mA(DC OR 1000 Hz)			
INSULATION RESISTANCE	100 V DC.	500 MΩ MIN.	×	—
VOLTAGE PROOF	500 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	×	—
MECHANICAL CHARACTERISTICS				
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs.	×	—
SHOCK	490 m/s² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.	② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—
ENVIRONMENTAL CHARACTERISTICS				
RAPID CHANGE OF TEMPERATURE	TEMPERATURE −55 →5 TO 35→+85 →5 TO 35°C TIME 30 →10 TO 15 →30 →10 TO15min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 ～ 95 %, 96 h.			
RESISTANCE TO SOLDERING HEAT	(1) REFLOW SOLDERING 《REFLOW AREA》 MAX 250℃ WITHIN 10 sec. MIN 220℃ WITHIN 70 sec 《PREHEATING AREA》 150℃ to 160 ℃ 60 sec. To 120 sec. PUT THROUGH IN REFLOW FUMACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE 350±5℃, FOR 5±1 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	×	—
SOLDERABILITY	SOLDERING TEMPERATURE : 235±5°C DURATION OF IMMERSION : SOLDERING, FOR 3 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	×	—

REMARKS
NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT.
NOTE2:NON-CONDENSING
NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.
Unless otherwise specified, refer to JIS C 5402

DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
J. Denpouya	J. Denpouya	T. Miyazaki	T. Miyazaki	
'03.03.05	'03.03.05	'03.03.05	'03.03.05	

Note QT:Qualification Test AT:Assurance Test ×:Applicable Test

HIROSE ELECTRIC CO., LTD.	SPECIFICATION SHEET	PART NO. DF14H-30P-1.25H(56)

CODE NO.(OLD)	DRAWING NO.	PART NO.	
CL	ELC4-161484-02	CL538-0188-0-56	1/1

FORM No. 231-1

TO